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- Contain Four Flip-Flops With Double-Rail Outputs
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators
- Package Options Include Plastic Small-Outline (D), Thin Shrink Small-Outline (PW), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

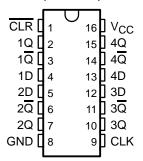
description

These monolithic positive-edge-triggered D-type flip-flops have a direct clear (CLR) input. The 'HC175 feature complementary outputs from each flip-flop.

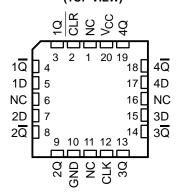
Information at the data (D) inputs meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going edge of CLK. When CLK is at either the high or low level, the D input has no effect at the output.

The SN54HC175 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74HC175 is characterized for operation from –40°C to 85°C.

SN54HC175 . . . J OR W PACKAGE SN74HC175 . . . D, N, OR PW PACKAGE (TOP VIEW)



SN54HC175 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE (each flip-flop)

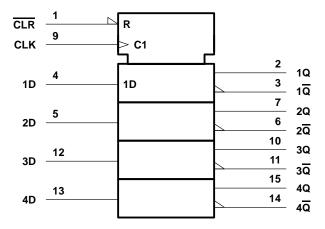
	INPUTS		OUTPUTS			
CLR	CLK	D	Q	Ø		
L	Х	Х	L	Н		
Н	\uparrow	Н	Н	L		
Н	\uparrow	L	L	Н		
Н	L	Χ	Q_0	\overline{Q}_0		



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

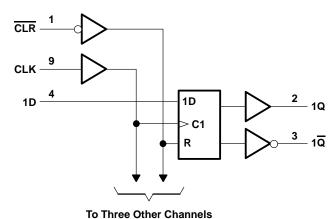


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, N, PW, and W packages.

absolute maximum ratings over operating free-air temperature range‡

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see		
Output clamp current, IOK (VO < 0 or VO > VC	C) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ _{JA} (see Note 2)	: D package	113°C/W
	N package	78°C/W
	PW package	149°C/W
Storage temperature range, T _{sto}		–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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recommended operating conditions

			SI	154HC17	75	SN74HC175			LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
VIH F		V _{CC} = 2 V	1.5			1.5			
	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		V _{CC} = 6 V	4.2			4.2			
		V _{CC} = 2 V	0		0.5	0		0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$	0		1.35	0		1.35	V
		V _{CC} = 6 V	0	0 1.8 0	1.8				
٧ _I	Input voltage		0		VCC	0		VCC	V
۷o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V	0		1000	0		1000	
t _t	Input transition (rise and fall) time	$V_{CC} = 4.5 \text{ V}$	0		500	0		500	ns
		V _{CC} = 6 V	0		400	0		400	
TA	Operating free-air temperature	_	-55		125	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST OF	NDITIONS	\ \ \	T _A = 25°C		;	SN54H	IC175	SN74H	C175	LINUT
PARAMETER	lesi co	ONDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		1
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	٧
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0	·	6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			8		160		80	μΑ
C _i			2 V to 6 V		3	10		10		10	pF

SN54HC175, SN74HC175 QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			V	T _A =	25°C	SN54F	IC175	SN74H	IC175	UNIT
			vcc	MIN	MAX	MIN	MAX	MIN	MAX	ONII
			2 V	0	6	0	4.2	0	5	
fclock	f _{clock} Clock frequency		4.5 V	0	31	0	21	0	25	MHz
			6 V	0	36	0	25	0	29	
		2 V	80		120		100			
		CLR low	4.5 V	16		24		20		ns
t _W Pulse duration	Dulas duration		6 V	14		20		17		
	Puise duration	CLK high or low	2 V	80		120		100		
			4.5 V	16		24		20		
			6 V	14		20		17		
			2 V	100		150		125		ns
		Data	4.5 V	20		30		25		
۱.	Setup time before CLK↑		6 V	17		25		21		
t _{su}	Setup time before CLN		2 V	100		150		125		
		CLR inactive	4.5 V	20		30		25		
			6 V	17		25		21		
	-		2 V	0		0		0	·	_
th	Hold time, data after CLK↑		4.5 V	0		0		0	·	ns
			6 V	0		0		0		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

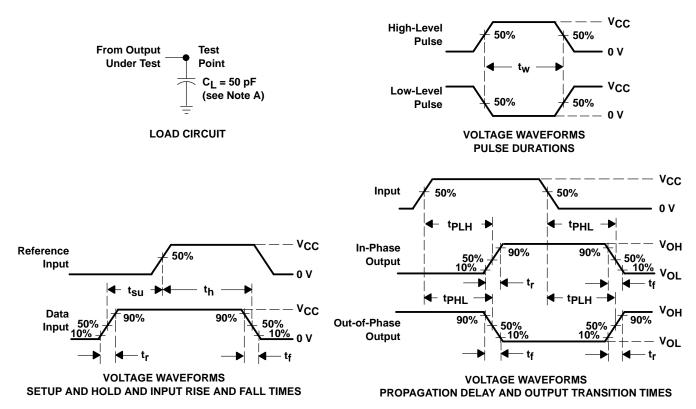
DADAMETED	FROM TO		V	T,	λ = 25°C	;	SN54H	IC175	SN74H	C175	LINIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	12		4.2		5		
f _{max}			4.5 V	31	50		21		25		MHz
			6 V	36	60		25		29		
			2 V		52	150		255		190	
	CLR	Any	4.5 V		15	30		45		38	ns
			6 V		13	26		38		32	
^t pd			2 V		58	150		255		190	115
	CLK	Any	4.5 V		16	30		45		38	
			6 V		13	26		38		32	
			2 V		38	75		110		90	
t _t		Any	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per flip-flop	No load	30	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_{O} = 50 \Omega$, $t_{r} = 6 \text{ ns}$, $t_{f} = 6 \text{ ns}$.
- C. For clock inputs, $f_{\mbox{max}}$ is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

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